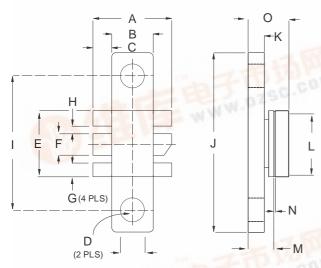
**TetraFET** 



# **D2015UK**

# METAL GATE RF SILICON FET

### **MECHANICAL DATA**



### **SOT 171**

PIN 1	SOURCE	PIN 2	SOURCE
PIN 3	GATE	PIN 4	DRAIN
DIN 5	SOLIBCE	DINI 6	SOLIDOE

DIM	mm	Tol.	Inches	Tol.
Α	10.92	0.25	0.430	0.001
В	5.84	0.08	0.230	0.003
С	2.54	0.08	0.100	0.003
D	3.30 dia	0.13	0.130 dia	0.05
Е	9.14	0.08	0.360	0.003
F	3.05	0.08	0.120	0.003
G	2.01	0.08	0.079	0.003
Н	1.04	0.08	0.041	0.003
	18.42	0.08	0.725	0.003
J	24.77	0.08	0.975	0.003
K	2.74	0.08	0.108	0.003
L	9.14	0.13	0.360	0.005
M	4.19	0.08	0.165	0.003
N	0.13	0.05	0.005	0.002
0	7.11	MAX	0.280	MAX

# GOLD METALLISED MULTI-PURPOSE SILICON DMOS RF FET 5W - 28V - 500MHz SINGLE ENDED

# **FEATURES**

- SIMPLIFIED AMPLIFIER DESIGN
- SUITABLE FOR BROAD BAND APPLICATIONS
- LOW Crss
- SIMPLE BIAS CIRCUITS
- LOW NOISE
- HIGH GAIN 13 dB MINIMUM

# **APPLICATIONS**

 VHF/UHF COMMUNICATIONS from DC to 2 GHz

# ABSOLUTE MAXIMUM RATINGS (T<sub>case</sub> = 25°C unless otherwise stated)

		2.21.1
$P_{D}$	Power Dissipation	29W
BV <sub>DSS</sub>	Drain - Source Breakdown Voltage	65V
BV <sub>GSS</sub>	Gate - Source Breakdown Voltage	±20V
I <sub>D(sat)</sub>	Drain Current	2A
T <sub>stg</sub>	Storage Temperature	−65 to 150°C
THE PROPERTY	Maximum Operating Junction Temperature	200°C



# **D2015UK**

# **ELECTRICAL CHARACTERISTICS** (T<sub>case</sub> = 25°C unless otherwise stated)

Parameter		Test Conditions		Min.	Тур.	Max.	Unit
B\/= a a	Drain-Source	V <sub>GS</sub> = 0	I <sub>D</sub> = 10mA	65			V
BV <sub>DSS</sub>	Breakdown Voltage	VGS - 0	ID = IOIIIA				\ \ \
I <sub>DSS</sub>	Zero Gate Voltage	\/ 29\/	V0			2	mA
	Drain Current	$V_{DS} = 28V$	$V_{GS} = 0$			2	IIIA
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> = 20V	$V_{DS} = 0$			1	μΑ
V <sub>GS(th)</sub>	Gate Threshold Voltage*	I <sub>D</sub> = 10mA	$V_{DS} = V_{GS}$	1		7	V
9 <sub>fs</sub>	Forward Transconductance*	V <sub>DS</sub> = 10V	I <sub>D</sub> = 0.4A	0.36			S
G <sub>PS</sub>	Common Source Power Gain	$P_O = 5W$		13			dB
η	Drain Efficiency	$V_{DS} = 28V$	$I_{DQ} = 0.2A$	40			%
VSWR	Load Mismatch Tolerance	f = 500MH:	<u>z</u>	20:1			_
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 0$	$V_{GS} = -5V$ f = 1MHz			20	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 28V	$V_{GS} = 0$ $f = 1MHz$			11	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	V <sub>DS</sub> = 28V	$V_{GS} = 0$ $f = 1MHz$			1	pF

<sup>\*</sup> Pulse Test: Pulse Duration = 300  $\mu s$ , Duty Cycle  $\leq$  2%

# **HAZARDOUS MATERIAL WARNING**

The ceramic portion of the device between leads and metal flange is beryllium oxide. Beryllium oxide dust is highly toxic and care must be taken during handling and mounting to avoid damage to this area.

### THESE DEVICES MUST NEVER BE THROWN AWAY WITH GENERAL INDUSTRIAL OR DOMESTIC WASTE.

# THERMAL DATA

R <sub>THj-case</sub>	Thermal Resistance Junction – Case	Max. 6.0°C / W
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